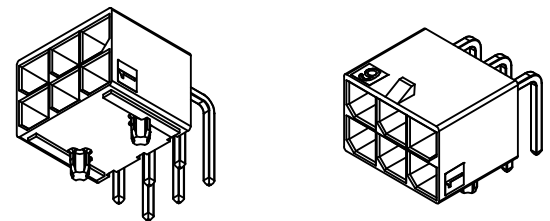
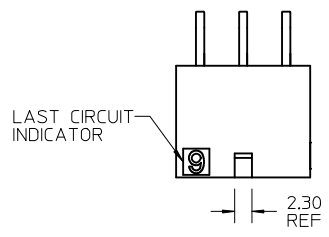
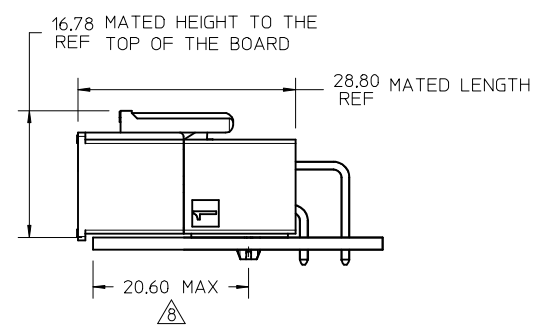
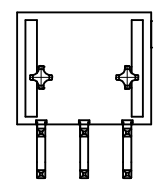
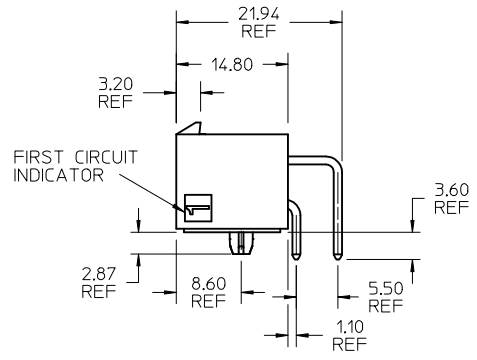
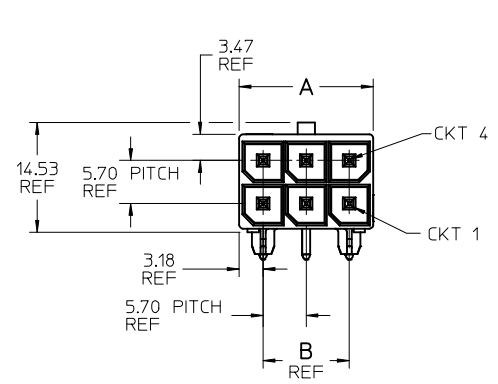


CKT SIZE	PART NO.	PLATING	DIM A	DIM B	DIM C
2	X 76825-0002	TIN	8.35	N/A	9.35
4	X 76825-0004	TIN	12.05	N/A	13.05
6	X 76825-0006	TIN	17.75	11.40	18.75
8	X 76825-0008	TIN	23.45	17.10	24.45
10	X 76825-0010	TIN	29.15	22.80	30.15
12	X 76825-0012	TIN	34.85	28.50	35.45
2	172064-0002	15 GOLD	8.35	N/A	9.35
4	172064-0004	15 GOLD	12.05	N/A	13.05
6	172064-0006	15 GOLD	17.75	11.40	18.75
8	172064-0008	15 GOLD	23.45	17.10	24.45
10	172064-0010	15 GOLD	29.15	22.80	30.15
12	172064-0012	15 GOLD	34.85	28.50	35.45
2	172064-1002	30 GOLD	8.35	N/A	9.35
4	172064-1004	30 GOLD	12.05	N/A	13.05
6	172064-1006	30 GOLD	17.75	11.40	18.75
8	172064-1008	30 GOLD	23.45	17.10	24.45
10	172064-1010	30 GOLD	29.15	22.80	30.15
12	172064-1012	30 GOLD	34.85	28.50	35.45



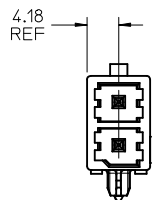
76825-0006 SHOWN



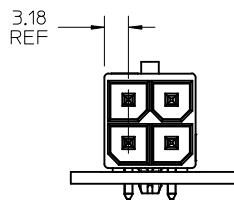
NOTES:

- MATERIAL:
HOUSING LCP, UL94V-0, GLOW WIRE CAPABLE PER IEC-60335-1 5TH EDITION, COLOR: BLACK.
TERMINAL: HIGH CONDUCTIVITY COPPER.
- TERMINAL PLATING:
(TIN) 1.52 MICROMETER MIN (60 MICROINCH MIN) REFLOWED MATTE TIN OVER
1.27 MICROMETER MIN (50 MICROINCH MIN) MIN NICKEL OVERALL.
(15 GOLD) 0.38 MICROMETER MIN (15 MICROINCH MIN) SELECTIVE GOLD ON CONTACT AREA
WITH 2.54 MICROMETER MIN (100 MICROINCHES MIN) SELECTIVE TIN ON SOLDER AREA
BOTH OVER 1.27 MICROMETER MIN (50 MICROINCHES MIN) NICKEL OVERALL.
(30 GOLD) 0.76 MICROMETER MIN (30 MICROINCH MIN) SELECTIVE GOLD ON CONTACT AREA
WITH 2.54 MICROMETER MIN (100 MICROINCHES MIN) SELECTIVE TIN ON SOLDER AREA
BOTH OVER 1.27 MICROMETER MIN (50 MICROINCHES MIN) NICKEL OVERALL.
- PRODUCT SPECIFICATION PS-76823-100.
- PACKAGING: TRAY PACKED PER MOLEX SPECIFICATION PK-76825-0000.
- PART MATES WITH MOLEX PART NUMBER 170001 AND 171692 SERIES.
- APPLICATION SPECIFICATION: AS-76823-100
- PARTS CONFORM TO CLASS "B" REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.
- ⚠️ TO AVOID INTERFERENCE BETWEEN RECEPTACLE AND PCB, HEADER MUST BE PLACED WITHIN 20.6 MAX FROM EDGE OF PCB AS SHOWN FOR 4 THROUGH 12 CIRCUITS. FOR 2 CIRCUIT PARTS THIS DIMENSION IS 15.1 MAX.

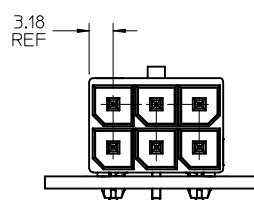
UPDATE NOTE 1 IEC NO: UCP2015-4319 2015/04/17 DRWN: DFOX 2015/04/17 CHKD: JBELL 2015/04/29 APPR: FSMITH	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DIMENSION STYLE MM ONLY DRAWN BY DATE MKARADIMAS 2010/11/15 CHECKED BY DATE	SCALE 2:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION
	MATERIAL NO. SEE CHART	APPROVED BY DATE APATEL 2012/06/13	MEGA-FIT R/A HEADER ASSY 2-12 CKT molex	
	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DOCUMENT NO. SD-76825-0100	SHEET NO. 1 OF 2	
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



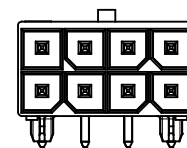
2 CIRCUIT



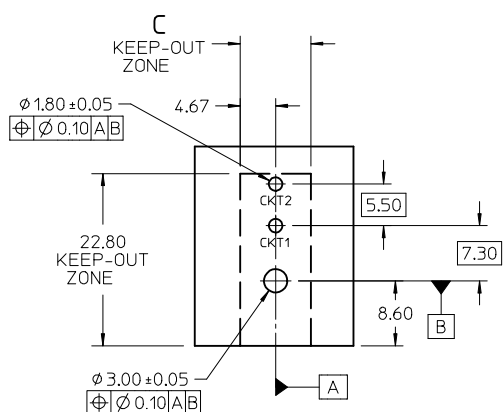
4 CIRCUIT



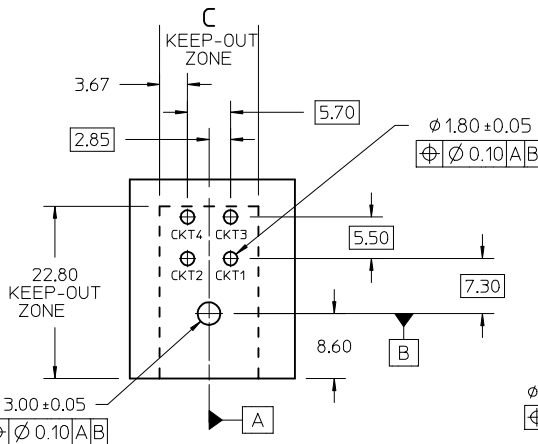
6-12 CIRCUIT



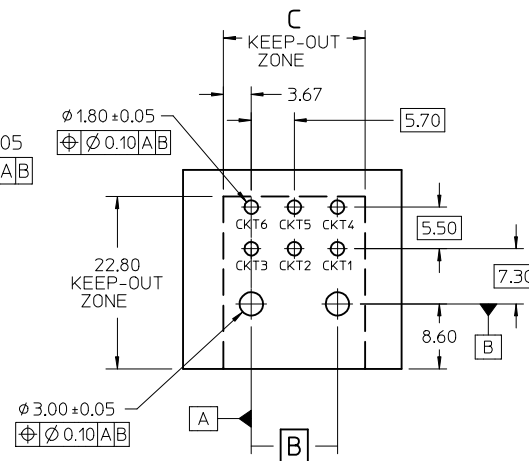
8 CIRCUIT



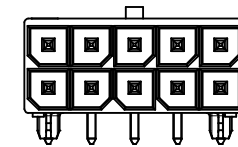
PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.58 MM/.062 IN
TO 2.36 MM/.093 IN



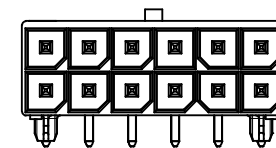
PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.58 MM/.062 IN
TO 2.36 MM/.093 IN



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.58 MM/.062 IN
TO 2.36 MM/.093 IN



10 CIRCUIT



12 CIRCUIT

SEE SHEET 1 EC NO: UCP2015-4319 DRWN: DFOX 2015/04/17 CHKD: BELL 2015/04/17 APPR: FSMITH 2015/04/29	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---		DRAWN BY DATE MKARADIMAS 2010/11/15		TITLE MEGA-FIT R/A HEADER ASSY 2-12 CKT			
		3 PLACES ± --- ± ---		CHECKED BY DATE		APPROVED BY DATE APATEL 2012/06/13			
		2 PLACES ± 0.25 ± ---		1 PLACE ± --- ± ---		MATERIAL NO. SEE CHART		SHEET NO. 2 OF 2	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS
 ANGULAR ±1/2°
 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION